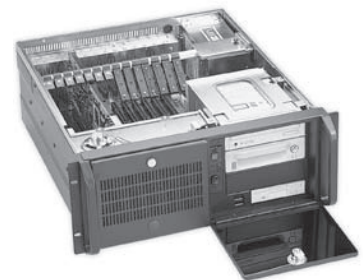


TD-Q67-12S-01

Specification

Spec item		Description
Form factor	SBC Form Factor	Full-size, slot CPU card
	Backplane Form Factor	1x PCIe x16 , 4 PCI-X and 4 PCI slots
System	CPU	Intel® Core i7-3770 [3.4GHz/MAX 3.9GHz]
	Chipset	Intel® Q67
	Memory	Samsung DDR3 4G PC3-12800
	CPU Socket	LGA1155
I/O Interface	Ethernet	LAN1: Intel® 82583V PCIe
		LAN2: Intel® 82579 PHY
	Digital I/O	8-bit Digital I/O
	Display	1 x VGA
Power	Power consumption	Supports by IEI AC-KIT-892HD-R10audio kit
		5V@3.98A, 12V@0.38A,Vcore_12V@7.81A, 3.3V@1.61A, 5VSB@0.15A 750W ATX power
Environment	Operating Temperature	-10oC ~ 60oC (14°F ~ 140°F)
	Humidity	5% ~ 95%, non-condensing
Storage	Storage	Samsung 850 PRO 256GB * 2 (RAID SYSTEM)
CPU Cooler	CPU Cooler	STANDARD 1155/1156 SLIM 쿨러
I/O Interface	I/O Interface	1 x SMBus
		1 x SMBus 4 x Internal RS-232/422/485
		1 x VGA
		1 x LPT
		1 x KB/MS
		6 x Internal USB 2.0
		1 x Internal RS-422/485
		2 x USB 2.0
Component	ODD	LiteOn DVD-MULTI
Weight	Weight	17.4 kg/21 kg(Net/Gross)



형 식

TD-Q67-12S-01

12-slot Full-size Rackmount industrial PC

483 x 177 x 510mm(19"x7.0"x20.1")